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1. Overview

This MCU is built using the high-performance silicon gate CMOS process using a R8C/Tiny Series CPU core and is packaged in a 32-pin plastic molded LQFP. This MCU operates using sophisticated instructions featuring a high level of instruction efficiency. With 1M bytes of address space, it is capable of executing instructions at high speed.
The data flash ROM (2 KB X 2 blocks) is embedded.

1.1 Applications

Electric household appliance, office equipment, housing equipment (sensor, security), general industrial equipment, audio, etc.

1.2 Performance Overview

Table 1.1. lists the performance outline of this MCU.

Table 1.1 Performance outline

Item		Performance
CPU	Number of basic instructions	89 instructions
	Minimum instruction execution time	50 ns (f(XIN) = 20 MHz, VCC = 3.0 to 5.5 V) 100 ns (f(XIN) = 10 MHz, VCC = 2.7 to 5.5 V)
	Operating mode	Single-chip
	Address space	1M bytes
	Memory capacity	See Table 1.2.
Peripheral function	Port	Input/Output: 22 (including LED drive port), Input: 2
	LED drive port	I/O port: 8
	Timer	Timer X: 8 bits x 1 channel, Timer Y: 8 bits x 1 channel, Timer Z: 8 bits x 1 channel (Each timer equipped with 8-bit prescaler) Timer C: 16 bits x 1 channel (Circuits of input capture and output compare)
	Serial interface	•1 channel Clock synchronous, UART •1 channel UART
	A/D converter	10-bit A/D converter: 1 circuit, 12 channels
	Watchdog timer	15 bits x 1 (with prescaler) Reset start function selectable
	Interrupt	Internal: 11 factors, External: 5 factors, Software: 4 factors, Priority level: 7 levels
	Clock generation circuit	2 circuits •Main clock generation circuit (Equipped with a built-in feedback resistor) •On-chip oscillator (high-speed, low-speed) On high-speed on-chip oscillator the frequency adjustment function is usable.
	Oscillation stop detection function	Main clock oscillation stop detection function
	Voltage detection circuit	Included
	Power on reset circuit	Included
Electrical characteristics	Supply voltage	VCC = 3.0 to 5.5V (f(XIN) = 20MHz) VCC = 2.7 to 5.5V (f(XIN) = 10MHz)
	Power consumption	Typ.9 mA (VCC = 5.0V, (f(XIN) = 20MHz) Typ.5 mA (VCC = 3.0V, (f(XIN) = 10MHz) Typ.35 µA (VCC = 3.0V, Wait mode, Peripheral clock stops) Typ.0.7 µA (VCC = 3.0V, Stop mode)
Flash memory	Program/erase supply voltage	VCC = 2.7 to 5.5 V
	Program/erase endurance	10,000 times (Data flash)
		1,000 times (Program ROM)
Operating ambient temperature		-20 to 85°C -40 to 85°C (D-version)
Package		32-pin plastic mold LQFP

1.3 Block Diagram

Figure 1.1 shows this MCU block diagram.

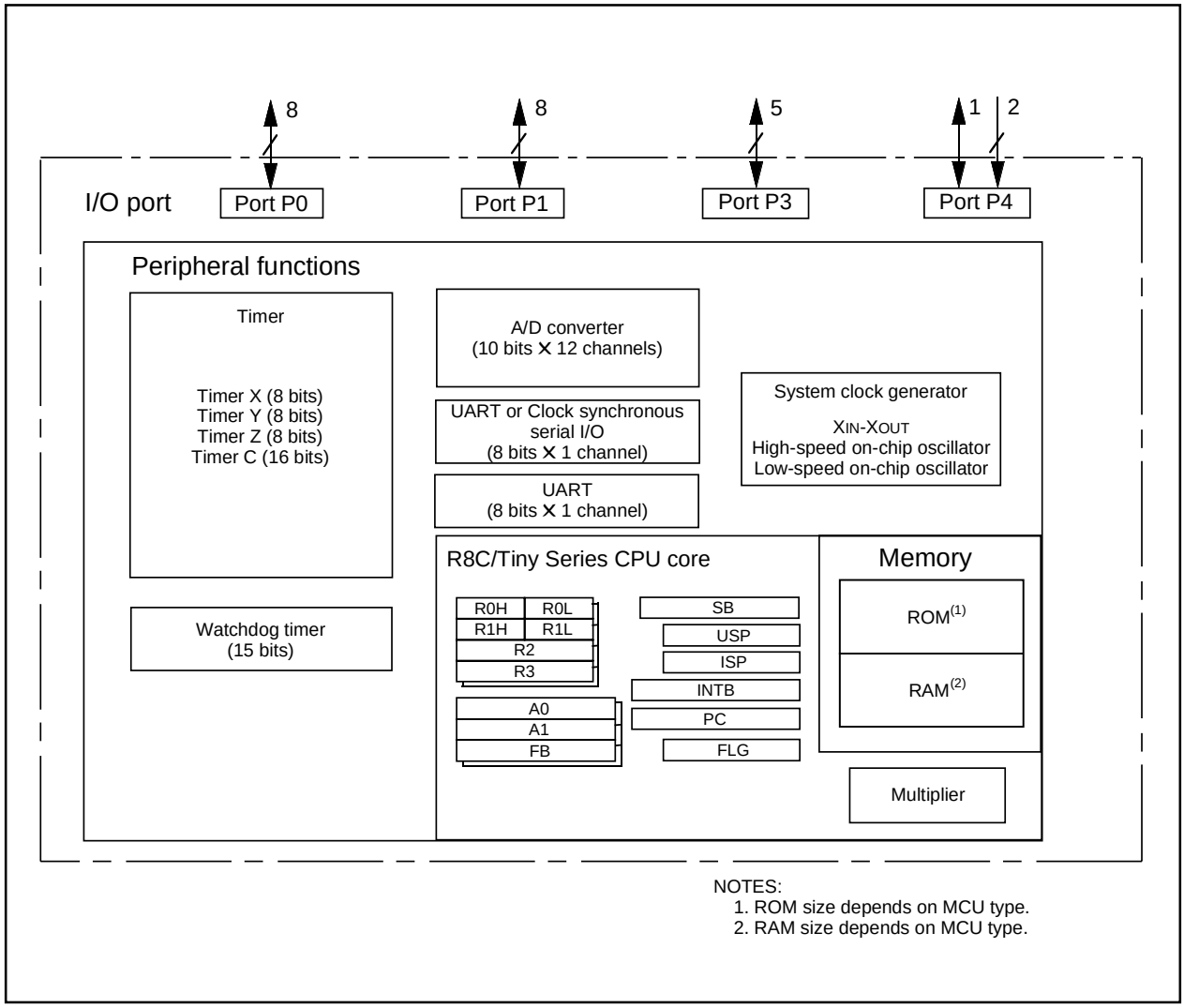


Figure 1.1 Block Diagram

1.4 Product Information

Table 1.2 lists the product information.

Table 1.2 Product Information

As of January 2006

Type No.	ROM capacity		RAM capacity	Package type	Remarks
	Program ROM	Data flash			
R5F21132FP	8K bytes	2K bytes x 2	512 bytes	PLQP0032GB-A	Flash memory version
R5F21133FP	12K bytes	2K bytes x 2	768 bytes	PLQP0032GB-A	
R5F21134FP	16K bytes	2K bytes x 2	1K bytes	PLQP0032GB-A	
R5F21132DFP	8K bytes	2K bytes x 2	512 bytes	PLQP0032GB-A	D version
R5F21133DFP	12K bytes	2K bytes x 2	768 bytes	PLQP0032GB-A	
R5F21134DFP	16K bytes	2K bytes x 2	1K bytes	PLQP0032GB-A	

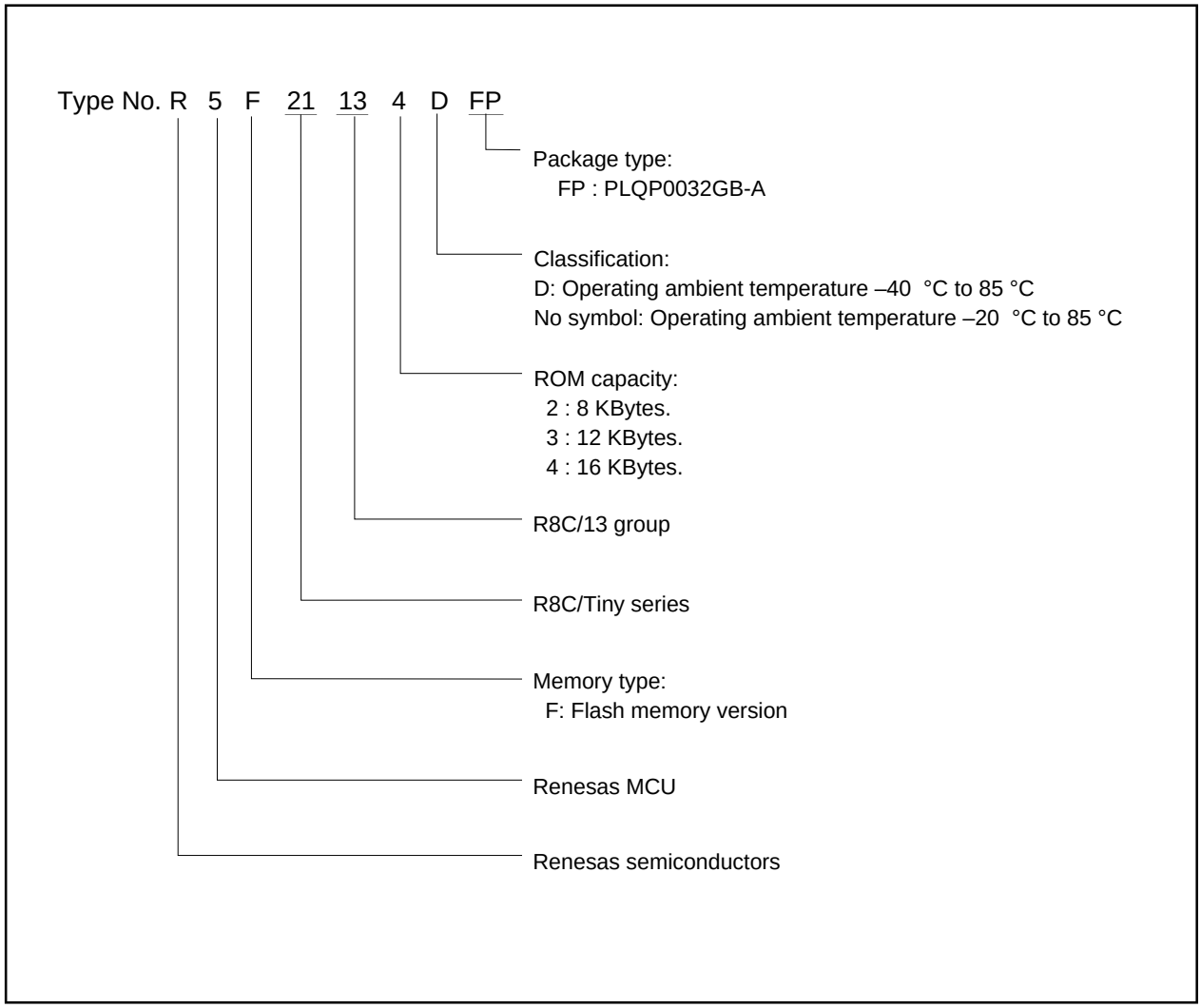
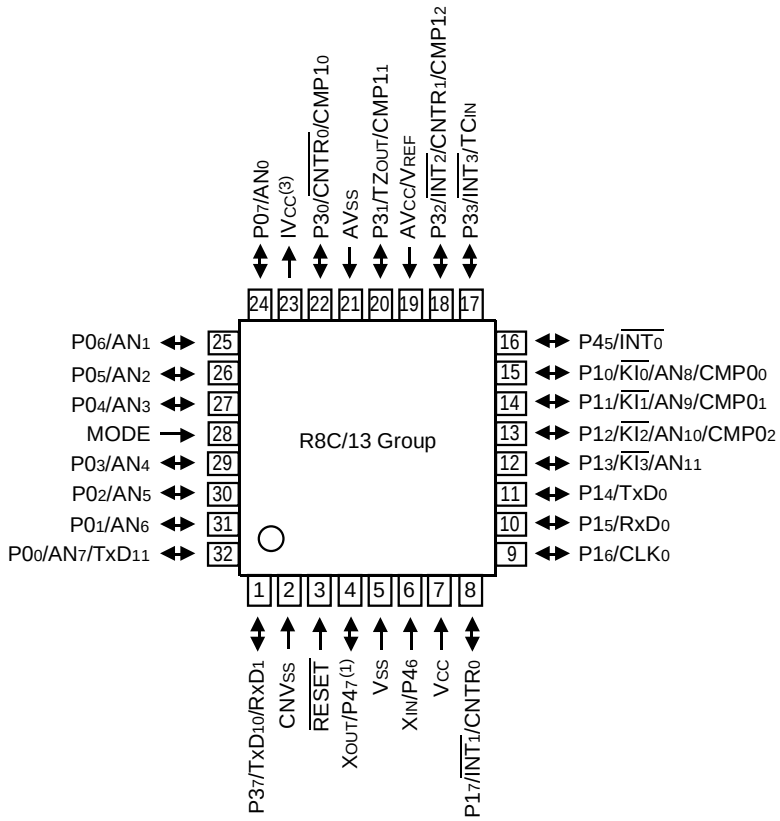


Figure 1.2 Type No., Memory Size, and Package

1.5 Pin Assignments

Figure 1.3 shows the pin configuration (top view).

PIN Assignments (top view)



NOTES:
1. P47 functions only as an input port.
2. When using On-chip debugger, do not use P00/AN7/TxD11 and P37/TxD10/RxD1 pins.
3. Do not connect IVcc to Vcc.

Package: PLQP0032GB-A (32P6U-A)

Figure 1.3 Pin Assignments (Top View)

1.6 Pin Description

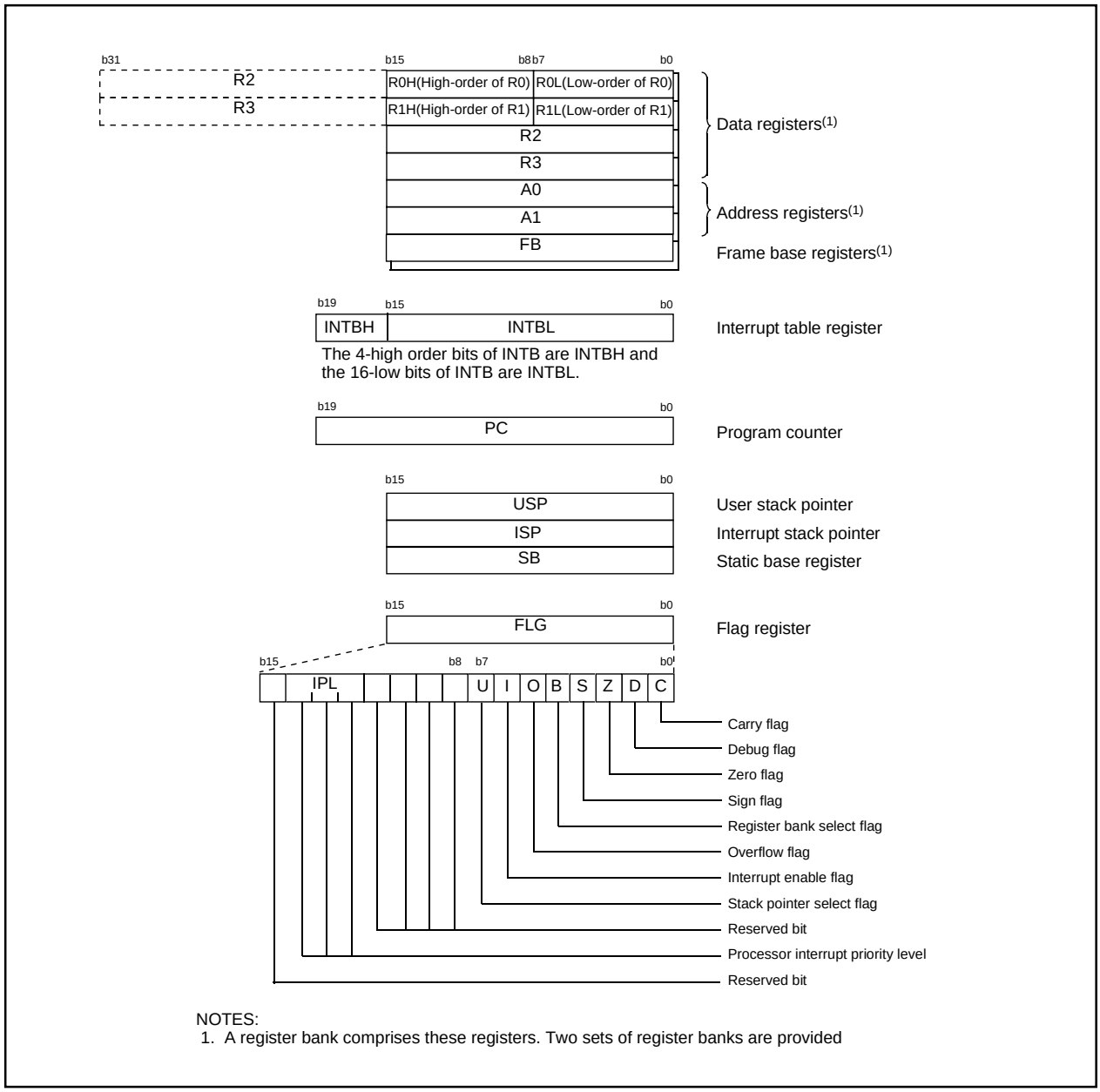
Table 1.3 shows the pin description

Table 1.3 Pin description

Signal name	Pin name	I/O type	Function
Power supply input	Vcc, Vss	I	Apply 2.7 V to 5.5 V to the Vcc pin. Apply 0 V to the Vss pin.
IVcc	IVcc	O	This pin is to stabilize internal power supply. Connect this pin to Vss via a capacitor (0.1 µF). Do not connect to Vcc.
Analog power supply input	AVcc, AVss	I	Power supply input pins for A/D converter. Connect the AVcc pin to Vcc. Connect the AVss pin to Vss. Connect a capacitor between pins AVcc and AVss.
Reset input	$\overline{\text{RESET}}$	I	Input “L” on this pin resets the MCU.
CNVss	CNVss	I	Connect this pin to Vss via a resistor.
MODE	MODE	I	Connect this pin to Vcc via a resistor.
Main clock input	XIN	I	These pins are provided for the main clock generating circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins. To use an externally derived clock, input it to the XIN pin and leave the XOUT pin open.
Main clock output	XOUT	O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT}}_0$ to $\overline{\text{INT}}_3$	I	$\overline{\text{INT}}$ interrupt input pins.
Key input interrupt input	$\overline{\text{KI}}_0$ to $\overline{\text{KI}}_3$	I	Key input interrupt pins.
Timer X	CNTR_0	I/O	Timer X I/O pin
	$\overline{\text{CNTR}}_0$	O	Timer X output pin
Timer Y	CNTR_1	I/O	Timer Y I/O pin
Timer Z	TZOUT	O	Timer Z output pin
Timer C	TCIN	I	Timer C input pin
	CMP0_0 to CMP0_2, CMP1_0 to CMP1_2	O	The timer C output pins
Serial interface	CLK_0	I/O	Transfer clock I/O pin.
	RxD_0, RxD_1	I	Serial data input pins.
	TxD_0, TxD_{10}, TxD_{11}	O	Serial data output pins.
Reference voltage input	VREF	I	Reference voltage input pin for A/D converter. Connect the VREF pin to Vcc.
A/D converter	AN_0 to AN_{11}	I	Analog input pins for A/D converter
I/O port	P0_0 to P0_7, P1_0 to P1_7, P3_0 to P3_3, P3_7, P4_5	I/O	These are 8-bit CMOS I/O ports. Each port has an I/O select direction register, allowing each pin in that port to be directed for input or output individually. Any port set to input can select whether to use a pull-up resistor or not by program. P1_0 to P1_7 also function as LED drive ports.
Input port	P4_6, P4_7	I	Port for input-only

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Register. The CPU contains 13 registers. Of these, R0, R1, R2, R3, A0, A1 and FB comprise a register bank. Two sets of register banks are provided.



NOTES:
1. A register bank comprises these registers. Two sets of register banks are provided

Figure 2.1 CPU Register

2.1 Data Registers (R0, R1, R2 and R3)

R0 is a 16-bit register for transfer, arithmetic and logic operations. The same applies to R1 to R3. The R0 can be split into high-order bit (R0H) and low-order bit (R0L) to be used separately as 8-bit data registers. The same applies to R1H and R1L as R0H and R0L. R2 can be combined with R0 to be used as a 32-bit data register (R2R0). The same applies to R3R1 as R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. They also are used for transfer, arithmetic and logic operations. The same applies to A1 as A0. A0 can be combined with A0 to be used as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register indicates the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC, 20 bits wide, indicates the address of an instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointer (SP), USP and ISP, are 16 bits wide each.

The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is a 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains a carry, borrow, or shift-out bit that has occurred in the arithmetic logic unit.

2.8.2 Debug Flag (D)

The D flag is for debug only. Set to “0”.

2.8.3 Zero Flag (Z)

The Z flag is set to “1” when an arithmetic operation resulted in 0; otherwise, “0”.

2.8.4 Sign Flag (S)

The S flag is set to “1” when an arithmetic operation resulted in a negative value; otherwise, “0”.

2.8.5 Register Bank Select Flag (B)

The register bank 0 is selected when the B flag is “0”. The register bank 1 is selected when this flag is set to “1”.

2.8.6 Overflow Flag (O)

The O flag is set to “1” when the operation resulted in an overflow; otherwise, “0”.

2.8.7 Interrupt Enable Flag (I)

The I flag enables a maskable interrupt.

An interrupt is disabled when the I flag is set to “0”, and are enabled when the I flag is set to “1”. The I flag is set to “0” when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to “0”, USP is selected when the U flag is set to “1”.

The U flag is set to “0” when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL, 3 bits wide, assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has greater priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

When write to this bit, set to “0”. When read, its content is indeterminate.

3. Memory

Figure 3.1 is a memory map of this MCU. This MCU provides 1-Mbyte address space from addresses 00000_{16} to $FFFFF_{16}$.

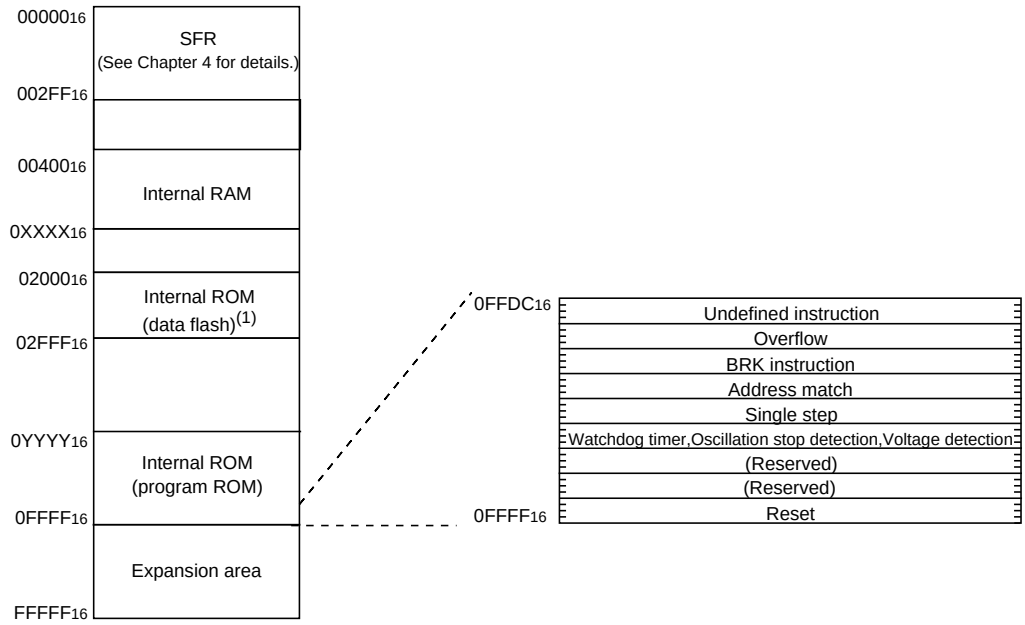
The internal ROM (program ROM) is allocated lower addresses beginning with address $0FFFF_{16}$. For example, a 16-Kbyte internal ROM is allocated addresses from $0C000_{16}$ to $0FFFF_{16}$.

The fixed interrupt vector table is allocated addresses $0FFDC_{16}$ to $0FFFF_{16}$. They store the starting address of each interrupt routine.

The internal ROM (data flash) is allocated addresses from 02000_{16} to $02FFF_{16}$.

The internal RAM is allocated higher addresses beginning with address 00400_{16}. For example, a 1-Kbyte internal RAM is allocated addresses 00400_{16} to $007FF_{16}$. The internal RAM is used not only for storing data, but for calling subroutines and stacks when interrupt request is acknowledged.

Special function registers (SFR) are allocated addresses 00000_{16} to $002FF_{16}$. The peripheral function control registers are located them. All addresses, which have nothing allocated within the SFR, are reserved area and cannot be accessed by users.



NOTES:
1. The data flash block A (2K bytes) and block B (2K bytes) are shown.
2. Blank spaces are reserved. No access is allowed.

Type name	Internal ROM		Internal RAM	
	Size	Address 0YYYY₁₆	Size	Address 0XXXX₁₆
R5F21134FP, R5F21134DFP	16K bytes	0C000₁₆	1K bytes	007FF₁₆
R5F21133FP, R5F21133DFP	12K bytes	0D000₁₆	768 bytes	006FF₁₆
R5F21132FP, R5F21132DFP	8K bytes	0E000₁₆	512 bytes	005FF₁₆

Figure 3.1 Memory Map

4. Special Function Register (SFR)

SFR(Special Function Register) is the control register of peripheral functions. Tables 4.1 to 4.4 list the SFR information

Table 4.1 SFR Information(1)(1)

Address	Register	Symbol	After reset
0000₁₆			
0001₁₆			
0002₁₆			
0003₁₆			
0004₁₆	Processor mode register 0(1)	PM0	00₁₆
0005₁₆	Processor mode register 1	PM1	00₁₆
0006₁₆	System clock control register 0	CM0	01101000₂
0007₁₆	System clock control register 1	CM1	00100000₂
0008₁₆	High-speed on-chip oscillator control register 0	HR0	00₁₆
0009₁₆	Address match interrupt enable register	AIER	XXXXXX00₂
000A₁₆	Protect register	PRCR	00XXX000₂
000B₁₆	High-speed on-chip oscillator control register 1	HR1	40₁₆
000C₁₆	Oscillation stop detection register	OCD	00000100₂
000D₁₆	Watchdog timer reset register	WDTR	XX₁₆
000E₁₆	Watchdog timer start register	WDTS	XX₁₆
000F₁₆	Watchdog timer control register	WDC	00011111₂
0010₁₆ 0011₁₆ 0012₁₆	Address match interrupt register 0	RMAD0	00₁₆ 00₁₆ X0₁₆
0013₁₆			
0014₁₆ 0015₁₆ 0016₁₆	Address match interrupt register 1	RMAD1	00₁₆ 00₁₆ X0₁₆
0017₁₆			
0018₁₆			
0019₁₆	Voltage detection register 1(2)	VCR1	00001000₂
001A₁₆	Voltage detection register 2(2)	VCR2	00₁₆(3) 10000000₂(4)
001B₁₆			
001C₁₆			
001D₁₆			
001E₁₆	$\overline{\text{INT0}}$ input filter select register	INT0F	XXXXX000₂
001F₁₆	Voltage detection interrupt register(2)	D4INT	00₁₆(3) 01000001₂(4)
0020₁₆			
0021₁₆			
0022₁₆			
0023₁₆			
0024₁₆			
0025₁₆			
0026₁₆			
0027₁₆			
0028₁₆			
0029₁₆			
002A₁₆			
002B₁₆			
002C₁₆			
002D₁₆			
002E₁₆			
002F₁₆			
0030₁₆			
0031₁₆			
0032₁₆			
0033₁₆			
0034₁₆			
0035₁₆			
0036₁₆			
0037₁₆			
0038₁₆			
0039₁₆			
003A₁₆			
003B₁₆			
003C₁₆			
003D₁₆			
003E₁₆			
003F₁₆			

X : Undefined
NOTES:
1. Blank spaces are reserved. No access is allowed.
2. Software reset or the watchdog timer reset does not affect this register.
3. Owing to Reset input.
4. In the case of $\overline{\text{RESET}}$ pin = H retaining.

Table 4.2 SFR Information(2)(1)

Address	Register	Symbol	After reset
0040₁₆			
0041₁₆			
0042₁₆			
0043₁₆			
0044₁₆			
0045₁₆			
0046₁₆			
0047₁₆			
0048₁₆			
0049₁₆			
004A₁₆			
004B₁₆			
004C₁₆			
004D₁₆	Key input interrupt control register	KUPIC	XXXXX000₂
004E₁₆	AD conversion interrupt control register	ADIC	XXXXX000₂
004F₁₆			
0050₁₆	Compare 1 interrupt control register	CMP1IC	XXXXX000₂
0051₁₆	UART0 transmit interrupt control register	S0TIC	XXXXX000₂
0052₁₆	UART0 receive interrupt control register	S0RIC	XXXXX000₂
0053₁₆	UART1 transmit interrupt control register	S1TIC	XXXXX000₂
0054₁₆	UART1 receive interrupt control register	S1RIC	XXXXX000₂
0055₁₆	$\overline{\text{INT2}}$ interrupt control register	INT2IC	XXXXX000₂
0056₁₆	Timer X interrupt control register	TXIC	XXXXX000₂
0057₁₆	Timer Y interrupt control register	TYIC	XXXXX000₂
0058₁₆	Timer Z interrupt control register	TZIC	XXXXX000₂
0059₁₆	$\overline{\text{INT1}}$ interrupt control register	INT1IC	XXXXX000₂
005A₁₆	$\overline{\text{INT3}}$ interrupt control register	INT3IC	XXXXX000₂
005B₁₆	Timer C interrupt control register	TCIC	XXXXX000₂
005C₁₆	Compare 0 interrupt control register	CMP0IC	XXXXX000₂
005D₁₆	$\overline{\text{INT0}}$ interrupt control register	INT0IC	XX00X000₂
005E₁₆			
005F₁₆			
0060₁₆			
0061₁₆			
0062₁₆			
0063₁₆			
0064₁₆			
0065₁₆			
0066₁₆			
0067₁₆			
0068₁₆			
0069₁₆			
006A₁₆			
006B₁₆			
006C₁₆			
006D₁₆			
006E₁₆			
006F₁₆			
0070₁₆			
0071₁₆			
0072₁₆			
0073₁₆			
0074₁₆			
0075₁₆			
0076₁₆			
0077₁₆			
0078₁₆			
0079₁₆			
007A₁₆			
007B₁₆			
007C₁₆			
007D₁₆			
007E₁₆			
007F₁₆			

X : Undefined
NOTES:
1. Blank spaces are reserved. No access is allowed.

Table 4.3 SFR Information(3)(1)

Address	Register	Symbol	After reset
0080₁₆	Timer Y, Z mode register	TYZMR	00₁₆
0081₁₆	Prescaler Y register	PREY	FF₁₆
0082₁₆	Timer Y secondary register	TYSC	FF₁₆
0083₁₆	Timer Y primary register	TYPR	FF₁₆
0084₁₆	Timer Y, Z waveform output control register	PUM	00₁₆
0085₁₆	Prescaler Z register	PREZ	FF₁₆
0086₁₆	Timer Z secondary register	TZSC	FF₁₆
0087₁₆	Timer Z primary register	TZPR	FF₁₆
0088₁₆			
0089₁₆			
008A₁₆	Timer Y, Z output control register	TYZOC	00₁₆
008B₁₆	Timer X mode register	TXMR	00₁₆
008C₁₆	Prescaler X register	PREX	FF₁₆
008D₁₆	Timer X register	TX	FF₁₆
008E₁₆	Count source set register	TCSS	00₁₆
008F₁₆			
0090₁₆ 0091₁₆	Timer C register	TC	00₁₆ 00₁₆
0092₁₆			
0093₁₆			
0094₁₆			
0095₁₆			
0096₁₆	External input enable register	INTEN	00₁₆
0097₁₆			
0098₁₆	Key input enable register	KIEN	00₁₆
0099₁₆			
009A₁₆	Timer C control register 0	TCC0	00₁₆
009B₁₆	Timer C control register 1	TCC1	00₁₆
009C₁₆ 009D₁₆	Capture, compare 0 register	TM0	00₁₆ 00₁₆(2)
009E₁₆ 009F₁₆	Compare 1 register	TM1	FF₁₆ FF₁₆
00A0₁₆	UART0 transmit/receive mode register	U0MR	00₁₆
00A1₁₆	UART0 bit rate register	U0BRG	XX₁₆
00A2₁₆ 00A3₁₆	UART0 transmit buffer register	U0TB	XX₁₆ XX₁₆
00A4₁₆	UART0 transmit/receive control register 0	U0C0	00001000₂
00A5₁₆	UART0 transmit/receive control register 1	U0C1	00000010₂
00A6₁₆ 00A7₁₆	UART0 receive buffer register	U0RB	XX₁₆ XX₁₆
00A8₁₆	UART1 transmit/receive mode register	U1MR	00₁₆
00A9₁₆	UART1 bit rate register	U1BRG	XX₁₆
00AA₁₆ 00AB₁₆	UART1 transmit buffer register	U1TB	XX₁₆ XX₁₆
00AC₁₆	UART1 transmit/receive control register 0	U1C0	00001000₂
00AD₁₆	UART1 transmit/receive control register 1	U1C1	00000010₂
00AE₁₆ 00AF₁₆	UART1 receive buffer register	U1RB	XX₁₆ XX₁₆
00B0₁₆	UART transmit/receive control register 2	UCON	00₁₆
00B1₁₆			
00B2₁₆			
00B3₁₆			
00B4₁₆			
00B5₁₆			
00B6₁₆			
00B7₁₆			
00B8₁₆			
00B9₁₆			
00BA₁₆			
00BB₁₆			
00BC₁₆			
00BD₁₆			
00BE₁₆			
00BF₁₆			

X : Undefined
NOTES:
1. Blank spaces are reserved. No access is allowed.
2. When output compare mode (the TCC13 bit in the TCC1 register = 1) is selected, the value after reset is set to "FFFF₁₆".

Table 4.4 SFR Information(4)(1)

Address	Register	Symbol	After reset
00C016 00C116	AD register	AD	XX16 XX16
00C216			
00C316			
00C416			
00C516			
00C616			
00C716			
00C816			
00C916			
00CA16			
00CB16			
00CC16			
00CD16			
00CE16			
00CF16			
00D016			
00D116			
00D216			
00D316			
00D416	AD control register 2	ADCON2	0016
00D516			
00D616	AD control register 0	ADCON0	00000XXX2
00D716	AD control register 1	ADCON1	0016
00D816			
00D916			
00DA16			
00DB16			
00DC16			
00DD16			
00DE16			
00DF16			
00E016	Port P0 register	P0	XX16
00E116	Port P1 register	P1	XX16
00E216	Port P0 direction register	PD0	0016
00E316	Port P1 direction register	PD1	0016
00E416			
00E516	Port P3 register	P3	XX16
00E616			
00E716	Port P3 direction register	PD3	0016
00E816	Port P4 register	P4	XX16
00E916			
00EA16	Port P4 direction register	PD4	0016
00EB16			
00EC16			
00ED16			
00EE16			
00EF16			
00F016			
00F116			
00F216			
00F316			
00F416			
00F516			
00F616			
00F716			
00F816			
00F916			
03FA16			
00FB16			
00FC16	Pull-up control register 0	PUR0	00XX00002
00FD16	Pull-up control register 1	PUR1	XXXXXX0X2
00FE16	Port P1 drive capacity control register	DRR	0016
00FF16	Timer C output control register	TCOUT	0016
01B316	Flash memory control register 4	FMR4	010000002
01B416			
01B516	Flash memory control register 1	FMR1	1000000X2
01B616			
01B716	Flash memory control register 0	FMR0	000000012
0FFFF16	Option function select register(2)	OFS	(Note 2)

X : Undefined
NOTES:
1. Blank columns, 010016 to 01B216 and 01B816 to 02FF16 are all reserved. No access is allowed.
2. The watchdog timer control bit is assigned. Refer to "Figure11.2 OFS, WDC, WDTR and WDTS registers" of Hardware Manual for details

5. Electrical Characteristics

Table 5.1 Absolute Maximum Ratings

Symbol	Parameter	Condition	Rated value	Unit
V_{CC}	Supply voltage	V_{CC}=AV_{CC}	-0.3 to 6.5	V
AV_{CC}	Analog supply voltage	V_{CC}=AV_{CC}	-0.3 to 6.5	V
V_I	Input voltage		-0.3 to V_{CC}+0.3	V
V_O	Output voltage		-0.3 to V_{CC}+0.3	V
P_d	Power dissipation	Topr=25 °C	300	mW
T_{opr}	Operating ambient temperature		-20 to 85 / -40 to 85 (D version)	°C
T_{stg}	Storage temperature		-65 to 150	°C

Table 5.2 Recommended Operating Conditions

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
V_{CC}	Supply voltage			2.7	—	5.5	V
AVcc	Analog supply voltage			—	V_{CC}(3)	—	V
Vss	Supply voltage			—	0	—	V
AVss	Analog supply voltage			—	0	—	V
V_{IH}	"H" input voltage			0.8V_{CC}	—	V_{CC}	V
V_{IL}	"L" input voltage			0	—	0.2V_{CC}	V
$I_{OH\ (sum)}$	"H" peak all output currents	Sum of all pins' IOH (peak)		—	—	-60.0	mA
$I_{OH\ (peak)}$	"H" peak output current			—	—	-10.0	mA
$I_{OH\ (avg)}$	"H" average output current			—	—	-5.0	mA
$I_{OL\ (sum)}$	"L" peak all output currents	Sum of all pins' IOL (peak)		—	—	60	mA
$I_{OL\ (peak)}$	"L" peak output current	Except $P1_0$ to $P1_7$		—	—	10	mA
		$P1_0$ to $P1_7$	Drive ability HIGH	—	—	30	mA
			Drive ability LOW	—	—	10	mA
$I_{OL\ (avg)}$	"L" average output current	Except $P1_0$ to $P1_7$		—	—	5	mA
		$P1_0$ to $P1_7$	Drive ability HIGH	—	—	15	mA
			Drive ability LOW	—	—	5	mA
f (X_{IN})	Main clock input oscillation frequency		3.0V ≤ Vcc ≤ 5.5V	0	—	20	MHz
			2.7V ≤ Vcc < 3.0V	0	—	10	MHz

NOTES:
1. V_{CC} = AV_{CC} = 2.7 to 5.5V at Topr = -20 to 85 °C / -40 to 85 °C, unless otherwise specified.
2. The typical values when average output current is 100ms.
3. Hold Vcc=AVcc.

Table 5.3 A/D Conversion Characteristics

Symbol	Parameter		Measuring condition	Standard			Unit
				Min.	Typ.	Max.	
–	Resolution		V_{ref} =V_{CC}	—	—	10	Bit
–	Absolute accuracy	10 bit mode	øAD=10 MHz, Vref=Vcc=5.0V	—	—	±3	LSB
		8 bit mode	øAD=10 MHz, Vref=Vcc=5.0V	—	—	±2	LSB
		10 bit mode	øAD=10 MHz, Vref=Vcc=3.3V(3)	—	—	±5	LSB
		8 bit mode	øAD=10 MHz, Vref=Vcc=3.3V(3)	—	—	±2	LSB
R_{LADDER}	Ladder resistance		V_{REF}=V_{CC}	10	—	40	kΩ
t_{CONV}	Conversion time	10 bit mode	øAD=10 MHz, Vref=Vcc=5.0V	3.3	—	—	µs
		8 bit mode	øAD=10 MHz, Vref=Vcc=5.0V	2.8	—	—	µs
V_{REF}	Reference voltage			—	V_{CC}(4)	—	V
V_{IA}	Analog input voltage			0	—	V_{ref}	V
–	A/D operating clock frequency(2)	Without sample & hold		0.25	—	10	MHz
		With sample & hold		1.0	—	10	MHz

NOTES:
1. V_{CC}=AV_{CC}=2.7 to 5.5V at Topr = -20 to 85 °C / -40 to 85 °C, unless otherwise specified.
2. If f_{AD} exceeds 10 MHz more, divide the f_{AD} and hold A/D operating clock frequency (Ø$_{AD}$) 10 MHz or below.
3. If the AVcc is less than 4.2V, divide the f_{AD} and hold A/D operating clock frequency (Ø$_{AD}$) f_{AD}/2 or below.
4. Hold Vcc=Vref.

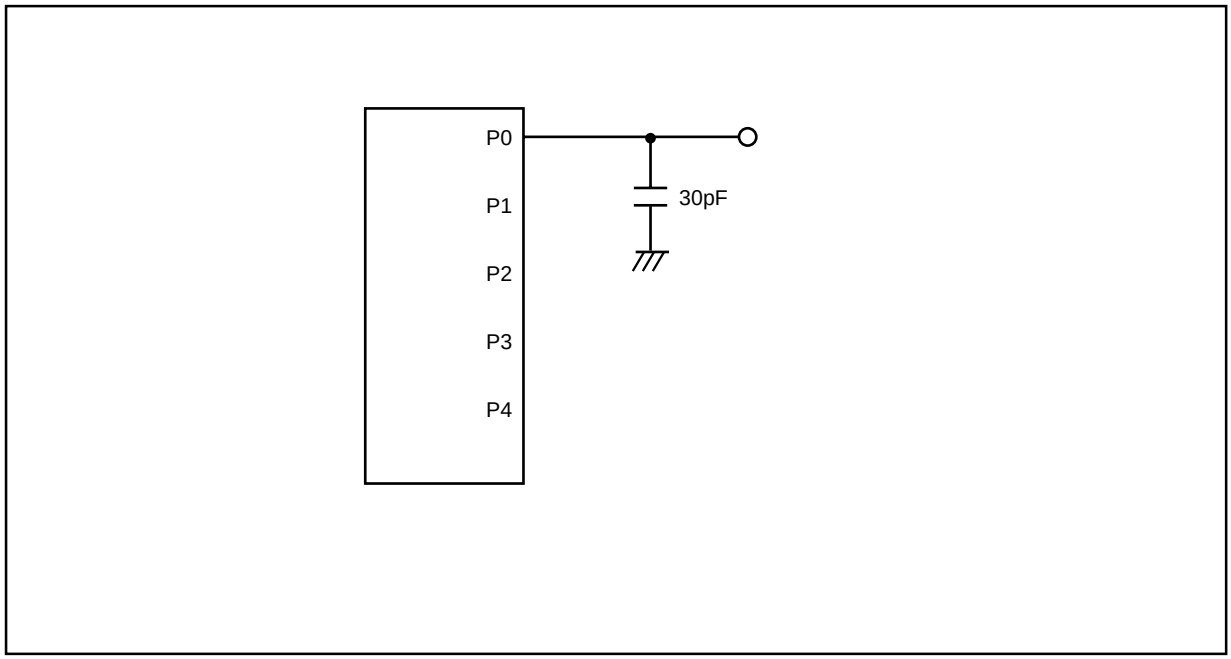


Figure 5.1 Port P0 to P4 measurement circuit

Table 5.4 Flash Memory (Program ROM) Electrical Characteristics

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max	
–	Program/Erase endurance(2)		1000(3)	—	—	times
–	Byte program time		—	50	—	µs
–	Block erase time		—	0.4	—	s
$t_{d(SR-ES)}$	Time delay from Suspend Request until Erase Suspend		—	—	8	ms
–	Erase Suspend Request Interval		10	—	—	ms
–	Program, Erase Voltage		2.7	—	5.5	V
–	Read Voltage		2.7	—	5.5	V
–	Program, Erase Temperature		0	—	60	°C
–	Data hold time(7)	Ambient temperature = 55 °C	20	—	—	year

NOTES:
1. Referenced to V_{CC}=AVcc=2.7 to 5.5V at Topr = 0°C to 60°C unless otherwise specified.
2. Definition of Program/Erase
   The endurance of Program/Erase shows a time for each block.
   If the program/erase number is “n” (n = 1000, 10000), “n” times erase can be performed for each block.
   For example, if performing one-byte write to the distinct addresses on Block A of 2K-byte block 2048 times and then erasing that block, the number of Program/Erase cycles is one time.
   However, performing multiple writes to the same address before an erase operation is prohibited (overwriting prohibited).
3. Numbers of Program/Erase cycles for which all electrical characteristics is guaranteed.
4. To reduce the number of Program/Erase cycles, a block erase should ideally be performed after writing in series as many distinct addresses (only one time each) as possible. If programming a set of 16 bytes, write up to 128 sets and then erase them one time. This will result in ideally reducing the number of Program/Erase cycles. Additionally, averaging the number of Program/Erase cycles for Block A and B will be more effective. It is important to track the total number of block erases and restrict the number.
5. If error occurs during block erase, attempt to execute the clear status register command, then the block erase command at least three times until the erase error disappears.
6. Customers desiring Program/Erase failure rate information should contact their Renesas technical support representative.
7. The data hold time includes time that the power supply is off or the clock is not supplied.

Table 5.5 Flash Memory (Data flash Block A, Block B) Electrical Characteristics(4)

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max	
–	Program/Erase endurance(2)		10000(3)	—	—	times
–	Byte program time(program/erase endurance ≤1000 times)		—	50	400	µs
–	Byte program time(program/erase endurance >1000 times)		—	65	—	µs
–	Block erase time(program/erase endurance ≤1000 times)		—	0.2	9	s
–	Block erase time(program/erase endurance >1000 times)		—	0.3	—	s
td(SR-ES)	Time delay from Suspend Request until Erase Suspend		—	—	8	ms
–	Erase Suspend Request Interval		10	—	—	ms
–	Program, Erase Voltage		2.7	—	5.5	V
–	Read Voltage		2.7	—	5.5	V
–	Program/Erase Temperature		-20(-40)(8)	—	85	°C
–	Data hold time(9)	Ambient temperature = 55 °C	20	—	—	year

NOTES:
1. Referenced to VCC=AVcc=2.7 to 5.5V at Topr = -20°C to 85°C / -40°C to 85°C unless otherwise specified.
2. Definition of Program/Erase
   The endurance of Program/Erase shows a time for each block.
   If the program/erase number is “n” (n = 1000, 10000), “n” times erase can be performed for each block.
   For example, if performing one-byte write to the distinct addresses on Block A of 2K-byte block 2048 times and then erasing that block, the number of Program/Erase cycles is one time.
   However, performing multiple writes to the same address before an erase operation is prohibited (overwriting prohibited).
3. Numbers of Program/Erase cycles for which all electrical characteristics is guaranteed.
4. Table 5.5 applies for Block A or B when the Program/Erase cycles are more than 1000. The byte program time up to 1000 cycles are the same as that of the program area (see Table 5.4).
5. To reduce the number of Program/Erase cycles, a block erase should ideally be performed after writing in series as many distinct addresses (only one time each) as possible. If programming a set of 16 bytes, write up to 128 sets and then erase them one time. This will result in ideally reducing the number of Program/Erase cycles. Additionally, averaging the number of Program/Erase cycles for Block A and B will be more effective. It is important to track the total number of block erases and restrict the number.
6. If error occurs during block erase, attempt to execute the clear status register command, then the block erase command at least three times until the erase error disappears.
7. Customers desiring Program/Erase failure rate information should contact their Renesas technical support representative.
8. -40 °C for D version.
9. The data hold time includes time that the power supply is off or the clock is not supplied.

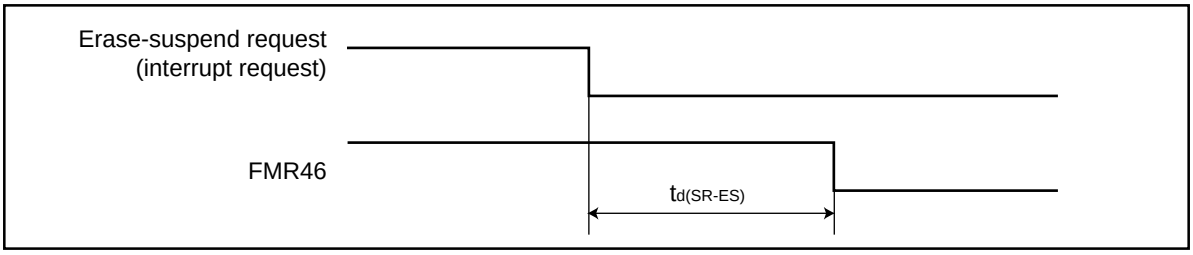


Figure 5.2 Time delay from Suspend Request until Erase Suspend

Table 5.6 Voltage Detection Circuit Electrical Characteristics

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
Vdet	Voltage detection level		3.3	3.8	4.3	V
	Voltage detection interrupt request generating time(2)			40		µs
	Voltage detection circuit self consumption current	VC27=1, VCC=5.0V		600		nA
td(E-A)	Waiting time until voltage detection circuit operation starts(3)				20	µs
Vccmin	Microcomputer operation voltage minimum value		2.7			V

NOTES:
1. The measuring condition is Vcc=AVcc=2.7V to 5.5V and Topr=-40°C to 85°C.
2. This shows the time until the voltage detection interrupt request is generated since the voltage passes Vdet.
3. This shows the required time until the voltage detection circuit operates when setting to "1" again after setting the VC27 bit in the VCR2 register to “0”.

Table 5.7 Reset Circuit Electrical Characteristics (When Using Hardware Reset 2(1, 3))

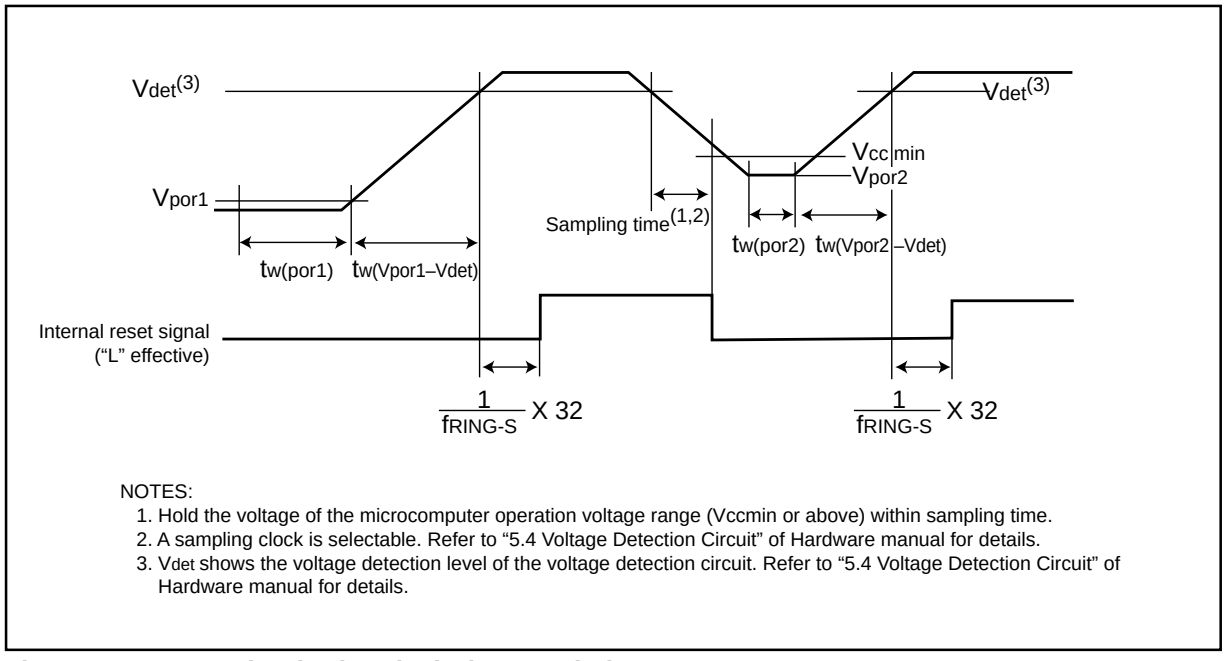
Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
Vpor2	Power-on reset valid voltage	–20°C ≤ Topr < 85°C	—	—	Vdet	V
tw(Vpor2-Vdet)	Supply voltage rising time when power-on reset is canceled(2)	–20°C ≤ Topr < 85°C, tw(por2) ≥ 0s(4)	—	—	100	ms

NOTES:
1. The voltage detection circuit which is embedded in a microcomputer is a factor to generate the hardware reset 2. Refer to 5.1.2 Hardware Reset 2 of Hardware Manual for details.
2. This condition is not applicable when using Vcc ≥ 1.0V.
3. When turning power on after the external power has been held below the valid voltage (Vpor1) for greater than 10 seconds, refer to Table 5.8 Reset Circuit Electrical Characteristics (When Not Using Hardware Reset 2).
4. tw(por2) is time to hold the external power below effective voltage (Vpor2).

Table 5.8 Reset Circuit Electrical Characteristics (When Not Using Hardware Reset 2)

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
Vpor1	Power-on reset valid voltage	–20°C ≤ Topr < 85°C	—	—	0.1	V
tW(Vpor1-Vdet)	Supply voltage rising time when power-on reset is canceled	0°C ≤ Topr ≤ 85°C, tw(por1) ≥ 10s(2)	—	—	100	ms
tW(Vpor1-Vdet)	Supply voltage rising time when power-on reset is canceled	–20°C ≤ Topr < 0°C, tw(por1) ≥ 30s(2)	—	—	100	ms
tW(Vpor1-Vdet)	Supply voltage rising time when power-on reset is canceled	–20°C ≤ Topr < 0°C, tw(por1) ≥ 10s(2)	—	—	1	ms
tW(Vpor1-Vdet)	Supply voltage rising time when power-on reset is canceled	0°C ≤ Topr ≤ 85°C, tw(por1) ≥ 1s(2)	—	—	0.5	ms

NOTES:
1. When not using hardware reset 2, use with Vcc ≥ 2.7V.
2. tw(por1) is time to hold the external power below effective voltage (Vpor1).



NOTES:
1. Hold the voltage of the microcomputer operation voltage range (Vccmin or above) within sampling time.
2. A sampling clock is selectable. Refer to “5.4 Voltage Detection Circuit” of Hardware manual for details.
3. Vdet shows the voltage detection level of the voltage detection circuit. Refer to “5.4 Voltage Detection Circuit” of Hardware manual for details.

Figure 5.3 Reset Circuit Electrical Characteristics

Table 5.9 High-speed On-Chip Oscillator Circuit Electrical Characteristics

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
—	High-speed on-chip oscillator frequency 1 / {td(HRoffset)+td(HR)} when the reset is released	VCC=5.0V, Topr=25 °C Set "40$_{16}$" in the HR1 register	—	8	—	MHz
td(HRoffset)	Settable high-speed on-chip oscillator minimum period	VCC=5.0V, Topr=25 °C Set "00$_{16}$" in the HR1 register	—	61	—	ns
td(HR)	High-speed on-chip oscillator period adjusted unit	Differences when setting "01$_{16}$" and "00$_{16}$" in the HR register	—	1	—	ns
—	High-speed on-chip oscillator frequency temperature dependence(1)	Frequency fluctuation in temperature range of -10 °C to 50 °C	—	±5	—	%
—	High-speed on-chip oscillator frequency temperature dependence(2)	Frequency fluctuation in temperature range of -40 °C to 85 °C	—	±10	—	%

NOTES:
1. The measuring condition is Vcc=AVcc=5.0 V and Topr=25 °C.

Table 5.10 Power Circuit Timing Characteristics

Symbol	Parameter	Measuring condition	Standard			Unit
			Min.	Typ.	Max.	
td(P-R)	Time for internal power supply stabilization during powering-on(2)		1		2000	µs
td(R-S)	STOP release time(3)				150	µs

NOTES:
1. The measuring condition is Vcc=AVcc=2.7 to 5.5 V and Topr=25 °C.
2. This shows the wait time until the internal power supply generating circuit is stabilized during power-on.
3. This shows the time until BCLK starts from the interrupt acknowledgement to cancel stop mode.

Table 5.11 Electrical Characteristics (1) [Vcc=5V]

Symbol	Parameter		Measuring condition		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	"H" output voltage	Except X_{OUT}	I_{OH}=-5mA		Vcc-2.0	—	Vcc	V
			I_{OH}=-200µA		Vcc-0.3	—	Vcc	V
		X_{OUT}	Drive capacity HIGH	I_{OH}=-1 mA	Vcc-2.0	—	Vcc	V
			Drive capacity LOW	I_{OH}=-500µA	Vcc-2.0	—	Vcc	V
V_{OL}	"L" output voltage	Except P10 to P17, X_{OUT}	I_{OL}= 5 mA		—	—	2.0	V
			I_{OL}= 200 µA		—	—	0.45	V
		P10 to P17	Drive capacity HIGH	I_{OL}= 15 mA	—	—	2.0	V
			Drive capacity LOW	I_{OL}= 5 mA	—	—	2.0	V
			Drive capacity LOW	I_{OL}= 200 µA	—	—	0.45	V
		X_{OUT}	Drive capacity HIGH	I_{OL}= 1 mA	—	—	2.0	V
			Drive capacity LOW	I_{OL}=500 µA	—	—	2.0	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT2}$, $\overline{INT3}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, $\overline{KI3}$, CNTR0, CNTR1, T_{CIN}, RxD0, RxD1, P45			0.2	—	1.0	V
		$\overline{RESET}$			0.2	—	2.2	V
I_{IH}	"H" input current		V_I=5V		—	—	5.0	µA
I_{IL}	"L" input current		V_I=0V		—	—	-5.0	µA
R_{PULLUP}	Pull-up resistance		V_I=0V		30	50	167	kΩ
R_{fXIN}	Feedback resistance	X_{IN}			—	1.0	—	MΩ
f_{RING-S}	Low-speed on-chip oscillator frequency				40	125	250	kHz
V_{RAM}	RAM retention voltage		At stop mode		2.0	—	—	V

NOTES:
1. Referenced to Vcc = AVcc = 4.2 to 5.5V at Topr = -20 to 85 °C / -40 to 85 °C, f(X_{IN})=20MHz unless otherwise specified.

Table 5.12 Electrical Characteristics (2) [Vcc=5V]

Symbol	Parameter		Measuring condition		Standard Min.	Standard Typ.	Standard Max.	Unit
I_{CC}	Power supply current (V_{CC}=3.3 to 5.5V) In single-chip mode, the output pins are open and other pins are V_{SS}		High-speed mode	X_{IN}=20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz No division	—	9	15	mA
				X_{IN}=16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz No division	—	8	14	mA
				X_{IN}=10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz No division	—	5	—	mA
			Medium-speed mode	X_{IN}=20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8	—	4	—	mA
				X_{IN}=16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8	—	3	—	mA
				X_{IN}=10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8	—	2	—	mA
			High-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator on=8 MHz Low-speed on-chip oscillator on=125 kHz No division	—	4	8	mA
				Main clock off High-speed on-chip oscillator on=8 MHz Low-speed on-chip oscillator on=125 kHz Division by 8	—	1.5	—	mA
			Low-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8	—	470	900	µA
			Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz When a WAIT instruction is executed(1) Peripheral clock operation VC27="0"	—	40	80	µA
			Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz When a WAIT instruction is executed(1) Peripheral clock off VC27="0"	—	38	76	µA
			Stop mode	Main clock off, Topr=-25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10="1" Peripheral clock off VC27="0"	—	0.8	3.0	µA

NOTES:
1. Timer Y is operated with timer mode.
2. Referenced to V_{CC} = AV_{CC} = 4.2 to 5.5V at Topr = -20 to 85 °C / -40 to 85 °C, f(X_{IN})=20MHz unless otherwise specified.

Timing requirements [Vcc=5V] (Unless otherwise noted: Vcc = 5V, Vss = 0V at Topr = 25 °C)

Table 5.13 XIN input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(XIN)	XIN input cycle time	50	–	ns
twH(XIN)	XIN input HIGH pulse width	25	–	ns
twL(XIN)	XIN input LOW pulse width	25	–	ns

Table 5.14 CNTR0 input, CNTR1 input, $\overline{\text{INT2}}$ input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(CNTR0)	CNTR0 input cycle time	100	–	ns
twH(CNTR0)	CNTR0 input HIGH pulse width	40	–	ns
twL(CNTR0)	CNTR0 input LOW pulse width	40	–	ns

Table 5.15 TCIN input, $\overline{\text{INT3}}$ input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(TCIN)	TCIN input cycle time	400(1)	–	ns
twH(TCIN)	TCIN input HIGH pulse width	200(2)	–	ns
twL(TCIN)	TCIN input LOW pulse width	200(2)	–	ns

NOTES:
1. When using the Timer C input capture mode, adjust the cycle time above (1/ Timer C count source frequency x 3).
2. When using the Timer C input capture mode, adjust the pulse width above (1/ Timer C count source frequency x 1.5).

Table 5.5 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tc(CK)	CLKi input cycle time	200	–	ns
tw(CKH)	CLKi input HIGH pulse width	100	–	ns
tw(CKL)	CLKi input LOW pulse width	100	–	ns
td(C-Q)	TxDi output delay time	–	80	ns
th(C-Q)	TxDi hold time	0	–	ns
tsu(D-C)	RxDi input setup time	35	–	ns
th(C-D)	RxDi input hold time	90	–	ns

Table 5.17 External interrupt $\overline{\text{INT0}}$ input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tw(INH)	$\overline{\text{INT0}}$ input HIGH pulse width	250(1)	–	ns
tw(INL)	$\overline{\text{INT0}}$ input LOW pulse width	250(2)	–	ns

NOTES:
1. When selecting the digital filter by the $\overline{\text{INT0}}$ input filter select bit, use the $\overline{\text{INT0}}$ input HIGH pulse width to the greater value,either (1/ digital filter clock frequency x 3) or the minimum value of standard.
2. When selecting the digital filter by the $\overline{\text{INT0}}$ input filter select bit, use the $\overline{\text{INT0}}$ input LOW pusle width to the greater value,either (1/ digital filter clock frequency x 3) or the minimum value of standard.

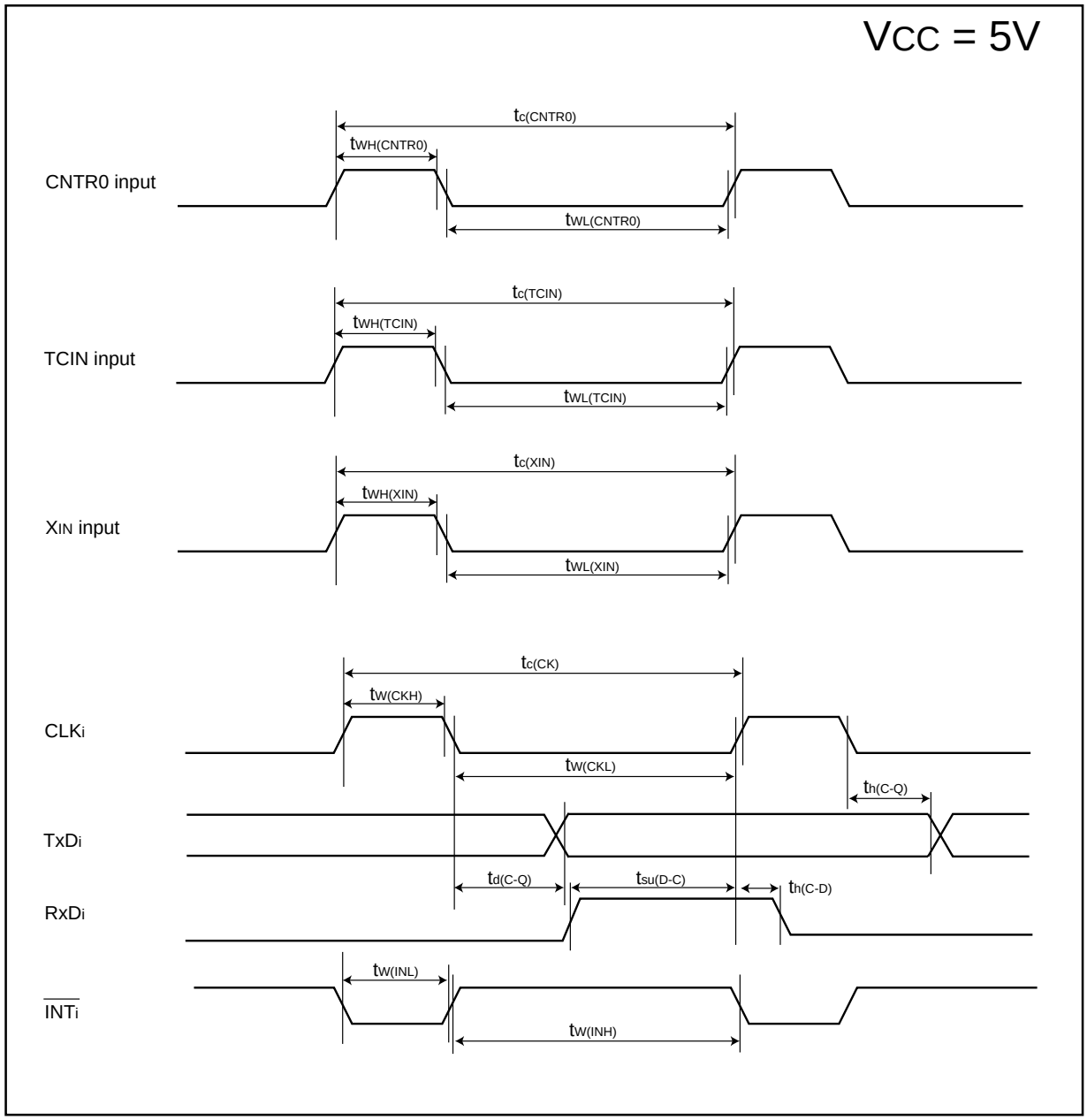


Figure 5.4 Vcc=5V timing diagram

Table 5.18 Electrical Characteristics (3) [Vcc=3V]

Symbol	Parameter		Measuring condition		Standard			Unit
					Min.	Typ.	Max.	
V_{OH}	"H" output voltage	Except X_{OUT}	I_{OH}=-1mA		V_{CC}-0.5	—	V_{CC}	V
		X_{OUT}	Drive capacity HIGH	I_{OH}=-0.1 mA	V_{CC}-0.5	—	V_{CC}	V
			Drive capacity LOW	I_{OH}=-50 µA	V_{CC}-0.5	—	V_{CC}	V
V_{OL}	"L" output voltage	Except P10 to P17, X_{OUT}	I_{OL}= 1 mA		—	—	0.5	V
		P10 to P17	Drive capacity HIGH	I_{OL}= 2 mA	—	—	0.5	V
			Drive capacity LOW	I_{OL}= 1 mA	—	—	0.5	V
		X_{OUT}	Drive capacity HIGH	I_{OL}= 0.1 mA	—	—	0.5	V
			Drive capacity LOW	I_{OL}=50 µA	—	—	0.5	V
V_{T+}-V_{T-}	Hysteresis	$\overline{INT0}$, $\overline{INT1}$, $\overline{INT2}$, $\overline{INT3}$, $\overline{KI0}$, $\overline{KI1}$, $\overline{KI2}$, KI3, CNTR0, CNTR1, TCIN, RxD0, RxD1, P45			0.2	—	0.8	V
		$\overline{RESET}$			0.2	—	1.8	V
I_{IH}	"H" input current		V_I=3V		—	—	4.0	µA
I_{IL}	"L" input current		V_I=0V		—	—	-4.0	µA
R_{PULLUP}	Pull-up resistance		V_I=0V		66	160	500	kΩ
R_{fXIN}	Feedback resistance	X_{IN}			—	3.0	—	MΩ
f_{RING-S}	Low-speed on-chip oscillator frequency				40	125	250	kHz
V_{RAM}	RAM retention voltage		At stop mode		2.0	—	—	V

NOTES:
1. Referenced to V_{CC} = AV_{CC} = 2.7 to 3.3V at Topr = -20 to 85 °C / -40 to 85 °C, f(X_{IN})=10MHz unless otherwise specified.

Table 5.19 Electrical Characteristics (4) [Vcc=3V]

Symbol	Parameter		Measuring condition		Standard			Unit
					Min.	Typ.	Max.	
I_{CC}	Power supply current (V_{CC}=2.7 to 3.3V) In single-chip mode, the output pins are open and other pins are V_{SS}		High-speed mode	X_{IN}=20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz No division	—	8	13	mA
				X_{IN}=16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz No division	—	7	12	mA
				X_{IN}=10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz No division	—	5	—	mA
			Medium-speed mode	X_{IN}=20 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8	—	3	—	mA
				X_{IN}=16 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8	—	2.5	—	mA
				X_{IN}=10 MHz (square wave) High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8	—	1.6	—	mA
			High-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator on=8 MHz Low-speed on-chip oscillator on=125 kHz No division	—	3.5	7.5	mA
				Main clock off High-speed on-chip oscillator on=8 MHz Low-speed on-chip oscillator on=125 kHz Division by 8	—	1.5	—	mA
			Low-speed on-chip oscillator mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz Division by 8	—	420	800	µA
			Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz When a WAIT instruction is executed(1) Peripheral clock operation VC27="0"	—	37	74	µA
			Wait mode	Main clock off High-speed on-chip oscillator off Low-speed on-chip oscillator on=125 kHz When a WAIT instruction is executed(1) Peripheral clock off VC27="0"	—	35	70	µA
			Stop mode	Main clock off, Topr=-25 °C High-speed on-chip oscillator off Low-speed on-chip oscillator off CM10="1" Peripheral clock off VC27="0"	—	0.7	3.0	µA

NOTES:
1. Timer Y is operated with timer mode.
2. Referenced to V_{CC} = AV_{CC} = 2.7 to 3.3V at Topr = -20 to 85 °C / -40 to 85 °C, f(X_{IN})=10MHz unless otherwise specified.

Timing requirements [VCC=3V] (Unless otherwise noted: VCC = 3V, VSS = 0V at Topr = 25 °C)

Table 5.20 XIN input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tC(XIN)	XIN input cycle time	100	–	ns
tWH(XIN)	XIN input HIGH pulse width	40	–	ns
tWL(XIN)	XIN input LOW pulse width	40	–	ns

Table 5.21 CNTR0 input, CNTR1 input, $\overline{\text{INT2}}$ input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tC(CNTR0)	CNTR0 input cycle time	300	–	ns
tWH(CNTR0)	CNTR0 input HIGH pulse width	120	–	ns
tWL(CNTR0)	CNTR0 input LOW pulse width	120	–	ns

Table 5.22 TCIN input, $\overline{\text{INT3}}$ input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tC(TCIN)	TCIN input cycle time	1200(1)	–	ns
tWH(TCIN)	TCIN input HIGH pulse width	600(2)	–	ns
tWL(TCIN)	TCIN input LOW pulse width	600(2)	–	ns

NOTES:
1. When using the Timer C input capture mode, adjust the cycle time above (1/ Timer C count source frequency x 3).
2. When using the Timer C input capture mode, adjust the pulse width above (1/ Timer C count source frequency x 1.5).

Table 5.23 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tC(CK)	CLKi input cycle time	300	–	ns
tW(CKH)	CLKi input HIGH pulse width	150	–	ns
tW(CKL)	CLKi input LOW pulse width	150	–	ns
td(C-Q)	TxDi output delay time	–	160	ns
th(C-Q)	TxDi hold time	0	–	ns
tsu(D-C)	RxDi input setup time	55	–	ns
th(C-D)	RxDi input hold time	90	–	ns

Table 5.24 External interrupt $\overline{\text{INT0}}$ input

Symbol	Parameter	Standard		Unit
		Min.	Max.	
tW(INH)	$\overline{\text{INT0}}$ input HIGH pulse width	380(1)	–	ns
tW(INL)	$\overline{\text{INT0}}$ input LOW pulse width	380(2)	–	ns

NOTES:
1. When selecting the digital filter by the $\overline{\text{INT0}}$ input filter select bit, use the $\overline{\text{INT0}}$ input HIGH pulse width to the greater value,either (1/ digital filter clock frequency x 3) or the minimum value of standard.
2 . When selecting the digital filter by the $\overline{\text{INT0}}$ input filter select bit, use the $\overline{\text{INT0}}$ input LOW pusle width to the greater value,either (1/ digital filter clock frequency x 3) or the minimum value of standard.

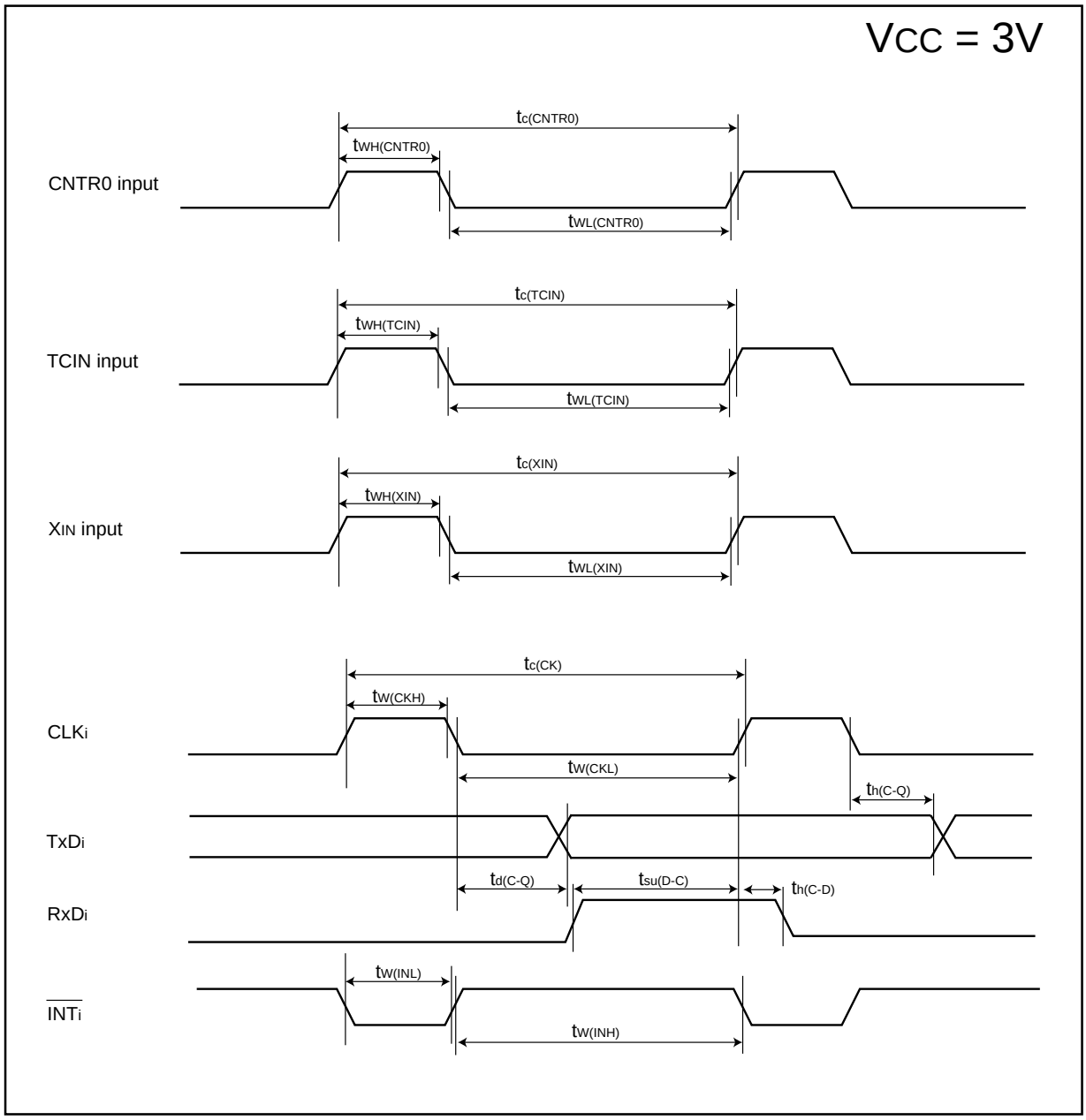
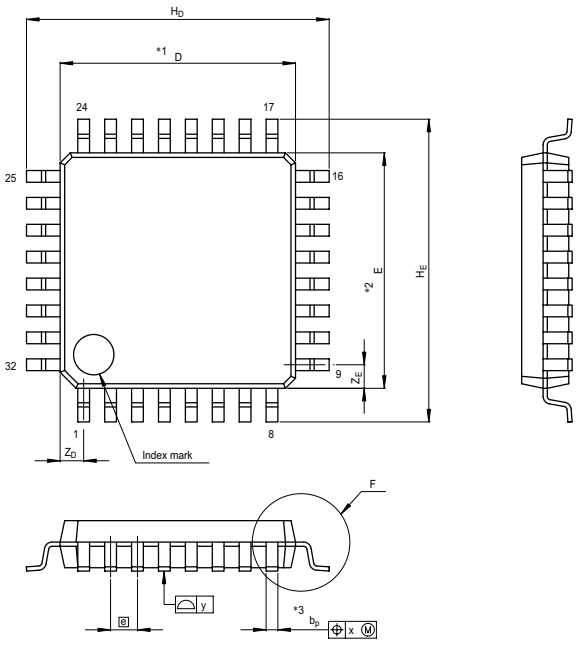
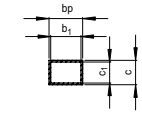


Figure 5.5 Vcc=3V timing diagram

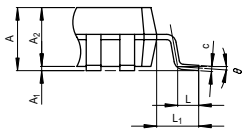
Package Dimensions

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP32-7x7-0.80	PLQP0032GB-A	32P6U-A	0.2g





Terminal cross section



Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	6.9	7.0	7.1
E	6.9	7.0	7.1
A_2	—	1.4	—
H_D	8.8	9.0	9.2
H_E	8.8	9.0	9.2
A	—	—	1.7
A_1	0	0.1	0.2
b_p	0.32	0.37	0.42
b_1	—	0.35	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.8	—
x	—	—	0.20
y	—	—	0.10
Z_D	—	0.7	—
Z_E	—	0.7	—
L	0.3	0.5	0.7
L_1	—	1.0	—

REVISION HISTORY	R8C/13 Group Datasheet

Rev.	Date	Description	
		Page	Summary
0.10	Oct 28, 2003		First edition issued
0.20	Dec05, 2003	5	Figure 1.3 revised
		10	Chapter 4, NOTES revised
		16	Table 5.4 revised Table 5.5 revised
		17	Table 5.6 revised Figure 5.3 added
		18	Table 5.8 revised Table 5.10 revised
		21	Figure 5.3 revised to Figure 5.4
		22	Table 5.17 revised
		25	Figure 5.4 revised to Figure 5.5
1.00	Sep 30, 2004	All pages	Words standardized (on-chip oscillator, serial interface, A/D)
		2	Table 1.1 revised
		5	Figure 1.3, NOTES 3 added
		6	Table 1.3 revised
		9	Figure 3.1, NOTES added
		10-13	One body sentence in chapter 4 added ; Titles of Table 4.1 to 4.4 added
		12	Table 4.3 revised ; Table 4.4 revised
		14	Table 5.2 revised
		15	Table 5.3 revised
		16	Table 5.4 and Table 5.5 revised
		17	Table 5.6, 5.7 and 5.8 revised ; Figure 5.3 revised
		18	Table 5.9 and 5.11 revised
		19	Table 5.12 revised
		20	Table 5.13 revised
		22	Table 5.18 revised
		23	Table 5.19 revised
		24	Table 5.20 and Table 5.24 revised
1.10	Apr.27.2005	4	Table 1.2, Figure 1.2 package name revised
		5	Figure 1.3 package name revised
		10	Table 4.1 revised
		12	Table 4.3 revised
		15	Table 5.3 partly revised
		16	Table 5.4, Table 5.5 partly added

Rev.	Date	Description	
		Page	Summary
1.10	Apr.27.2005	17	Table 5.7, 5.8 revised
		18	Table 5.10, Table 5.11 partly revised
		22	Table 5.18 partly revised
		26	Package Dimensions revised
1.20	Jan.27.2006	2	Table 1.1 Performance outline revised
		3	Figure 1.1 Block diagram partly revised
		4	1.4 Product Information, title of Table 1.2 "Product List" → "Product Informaton" revised ROM capacity; "Program area" → "Program ROM", "Data area" → "Data flash" revised Figure 1.2 Type No., Memory Size, and Package partly revised
		6	Table 1.3 Pin description revised
		7-8	2 Central Processing Unit (CPU) revised Figure 2.1 CPU register revised
		9	3 Memory, Figure 3.1 Memory Map; "Program area" → "Program ROM", "Data area" → "Data flash" revised
		10	Table 4.1 SFR Information(1) NOTES:1 revised
		11	Table 4.2 SFR Information(2) NOTES:1 revised
		12	Table 4.3 SFR Information(3); 0081_{16}: "Prescaler Y" → "Prescaler Y Register" 0082_{16}: "Timer Y Secondary" → "Timer Y Secondary Register" 0083_{16}: "Timer Y Primary" → "Timer Y Primary Register" 0085_{16}: "Prescaler Z" → "Prescaler Z Register" 0086_{16}: "Timer Z Secondary" → "Timer Z Secondary Register" 0087_{16}: "Timer Z Primary" → "Timer Z Primary Register" $008C_{16}$: "Prescaler X" → "Prescaler X Register" revised NOTES:1, 2 revised
		13	Table 4.4 SFR Information(4) NOTES:1 revised
		14	Table 5.2 Recommended Operating Conditions; NOTES: 1, 2, 3 revised
		15	Table 5.3 A/D Conversion Characteristics; "A/D operation clock frequency" → "A/D operating clock frequency" revised NOTES: 1, 2, 3, 4 revised
		16	Table 5.4 Flash Memory (Program ROM) Electrical Characteristics; "Data retention duration" → "Data hold time" revised "Topr" → "Ambient temperature" NOTES: 1 to 7 added Measuring condition of byte program time and block erase time deleted
		17	Table 5.5 Flash Memory (Data flash Block A, Block B) Electrical characteristics "Data retention duration" → "Data hold time" revised "Topr" → "Ambient temperature" NOTES: 1, 3 revised, NOTES: 9 added Measuring condition of byte program time and block erase time deleted
		18	Table 5.7 Reset Circuit Electrical Characteristics (When Using Hardware Reset 2) NOTES: 3 revised
		19	Table 5.9 High-speed On-Chip Oscillator Circuit Electrical Characteristics; "High-speed on-chip oscillator temperature dependence" → "High-speed on-chip oscillator frequency temperature dependence" revised Table 5.11 Electrical Characteristics (1) [V_{CC}=5V]; "$P1_0$ to $P1_7$ Except X_{OUT}" → "Except $P1_0$ to $P1_7$, X_{OUT}" revised

Rev.	Date	Description	
		Page	Summary
1.20	Jan.27.2006	20	Table 5.12 Electrical Characteristics (2) [V_{CC}=5V]; NOTES: 1, 2 revised Measuring condition Stop mode: “Topr=-25 °C” added
		23	Table 5.18 Electrical Characteristics (3) [V_{CC}=3V] “$P1_0$ to $P1_7$ Except X_{OUT}” → “Except $P1_0$ to $P1_7$, X_{OUT}” revised
		24	Table 5.19 Electrical Characteristics (4) [V_{CC}=3V] NOTES: 1, 2 revised Measuring condition Stop mode: “Topr=-25 °C” added

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